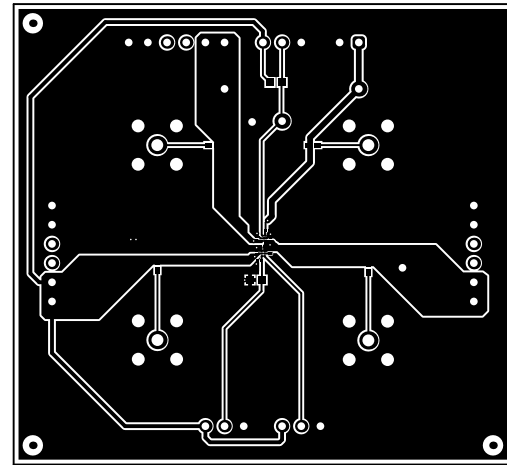
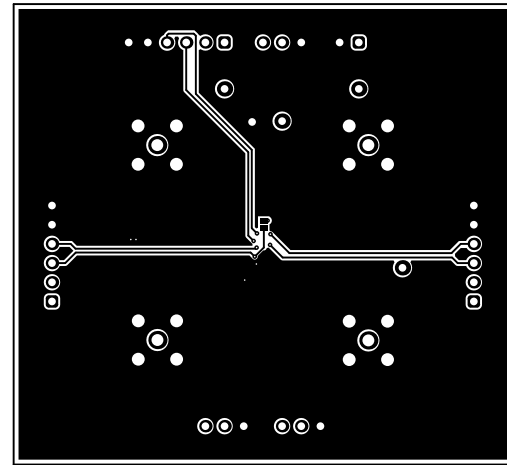


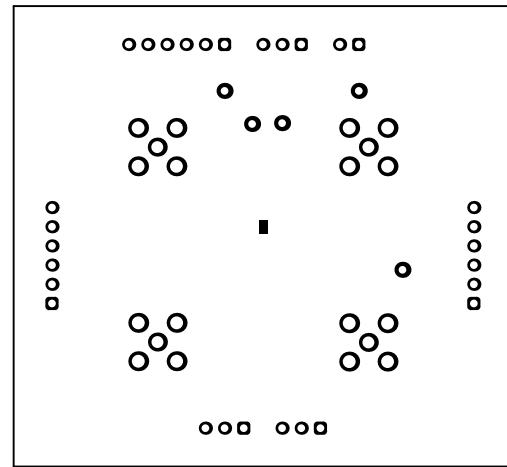
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-01566 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: TIDA-01566 | | |
| PLOT NAME = Top Solder Mask | GENERATED : 6/4/2018 11:26:45 AM | TEXAS INSTRUMENTS | |



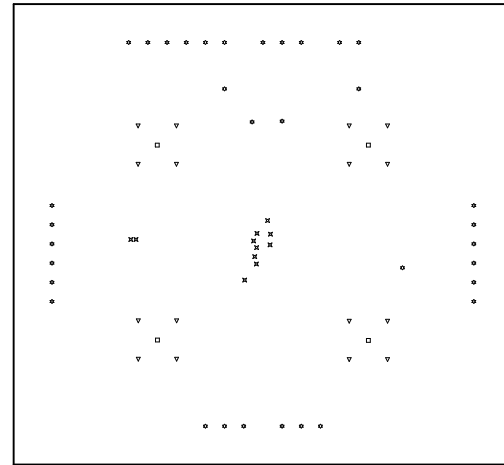
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-01566 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: TIDA-01566 | | |
| PLOT NAME = Top Layer | GENERATED : 6/4/2018 11:26:46 AM | TEXAS INSTRUMENTS | |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-01566 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: TIDA-01566 | | |
| PLOT NAME = Bottom Layer | GENERATED : 6/4/2018 11:26:47 AM | TEXAS INSTRUMENTS | |

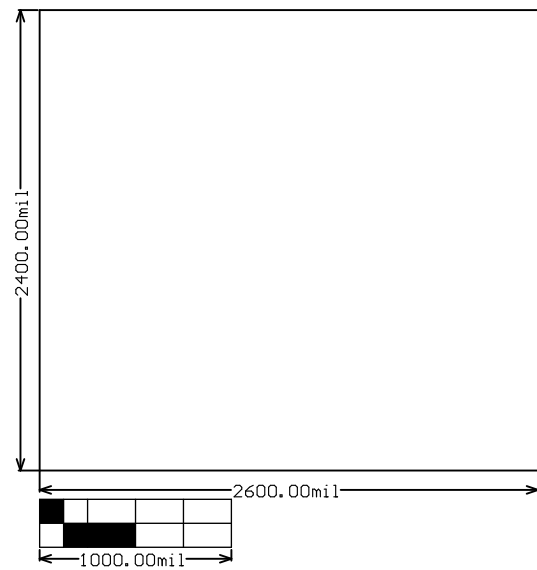


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-01566 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: TIDA-01566 | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 6/4/2018 11:26:48 AM | TEXAS INSTRUMENTS | |



| Symbol | Quantity | Finished Hole Size | Plated | Hole Type | Drill Layer Pair | Hole Tolerance |
|--------|----------|--------------------|--------|-----------|--------------------------|----------------|
| ⊗ | 11 | 8.00mil (0.203mm) | PTH | Round | Top Layer - Bottom Layer | |
| ⊛ | 34 | 40.00mil (1.016mm) | PTH | Round | Top Layer - Bottom Layer | |
| □ | 4 | 62.00mil (1.575mm) | PTH | Round | Top Layer - Bottom Layer | |
| ∇ | 16 | 67.00mil (1.702mm) | PTH | Round | Top Layer - Bottom Layer | |
| | 65 Total | | | | | |

| | | | |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-01566 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = | TID #: TIDA-01566 | | |
| PLOT NAME = Drill Drawing | GENERATED : 6/4/2018 | 11:26:49 AM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDA-01566 | REV: E1 | SVN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: TIDA-01566 | | |
| PLOT NAME = Board Dimensions | GENERATED : 6/4/2018 | 11:26:50 AM | TEXAS INSTRUMENTS |

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